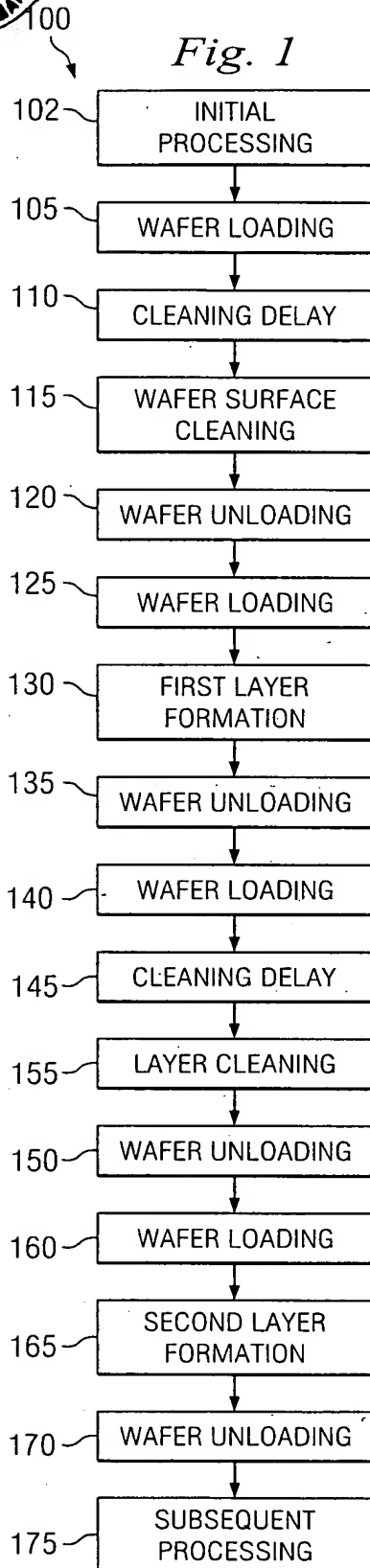




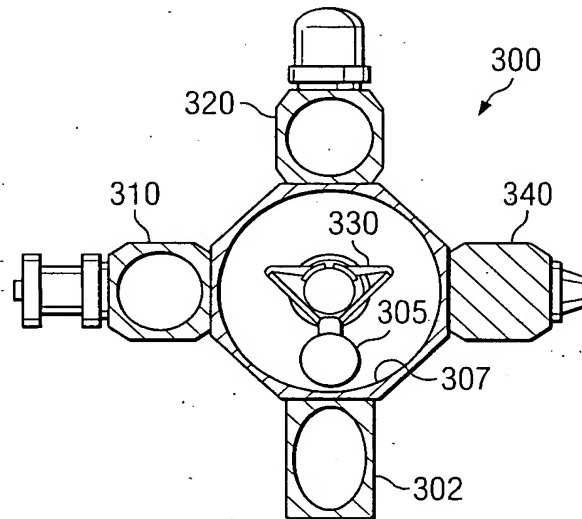
24061.42  
SEMICONDUCTOR WAFER MANUFACTURING  
METHODS EMPLOYING CLEANING DELAY PERIOD

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*Fig. 1*



*Fig. 3*



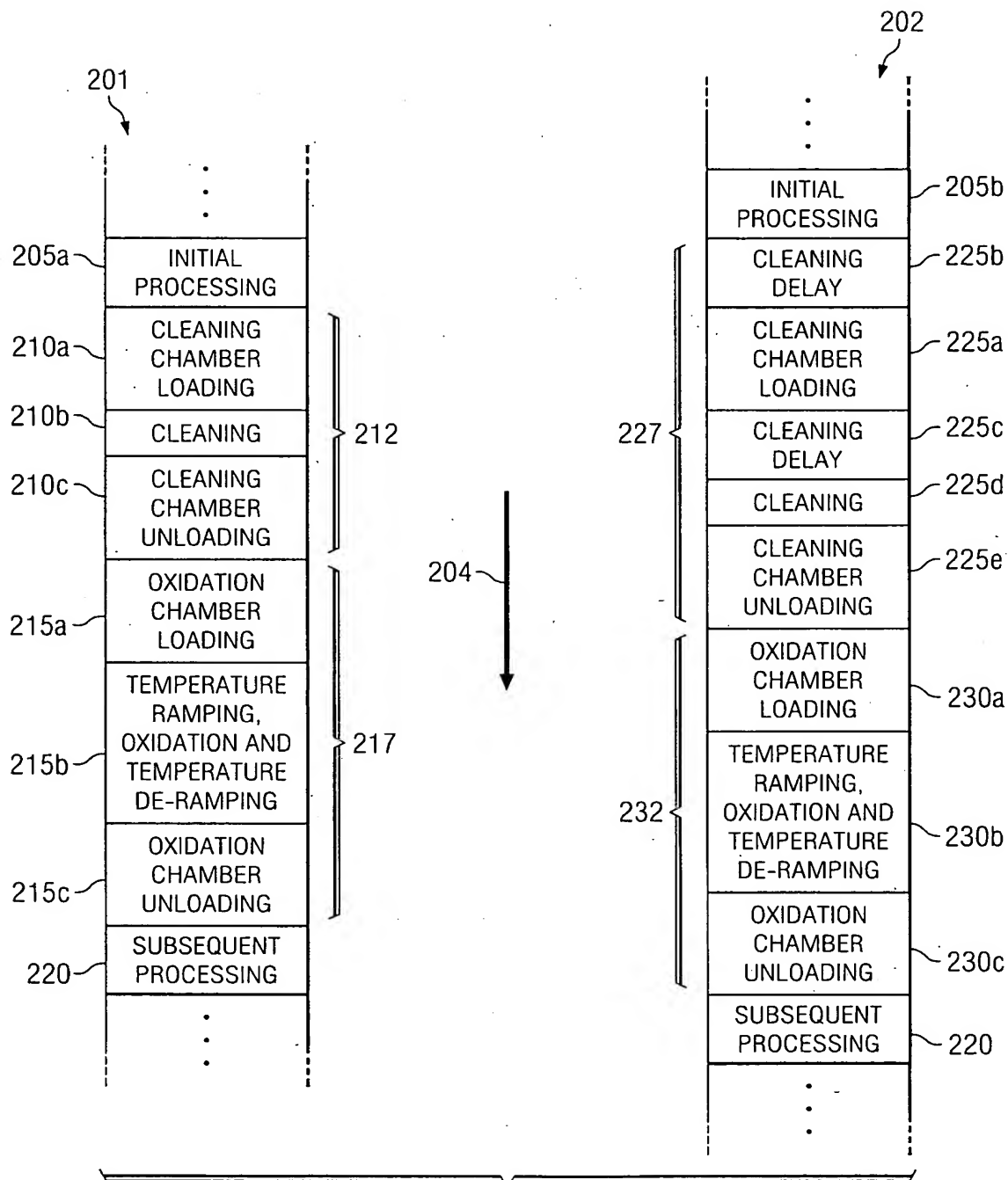


Fig. 2